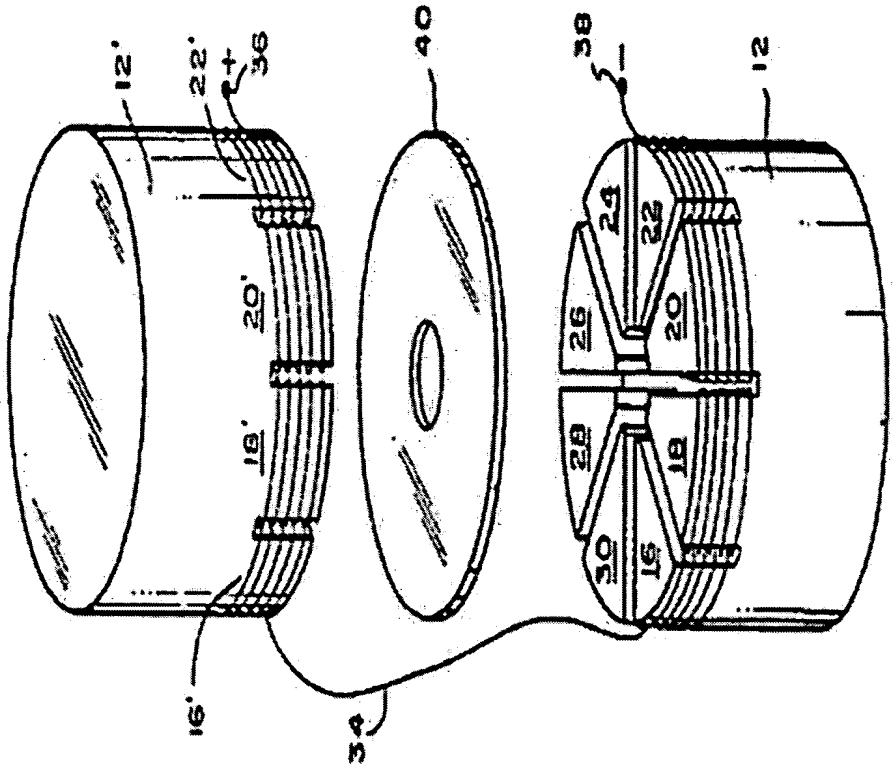
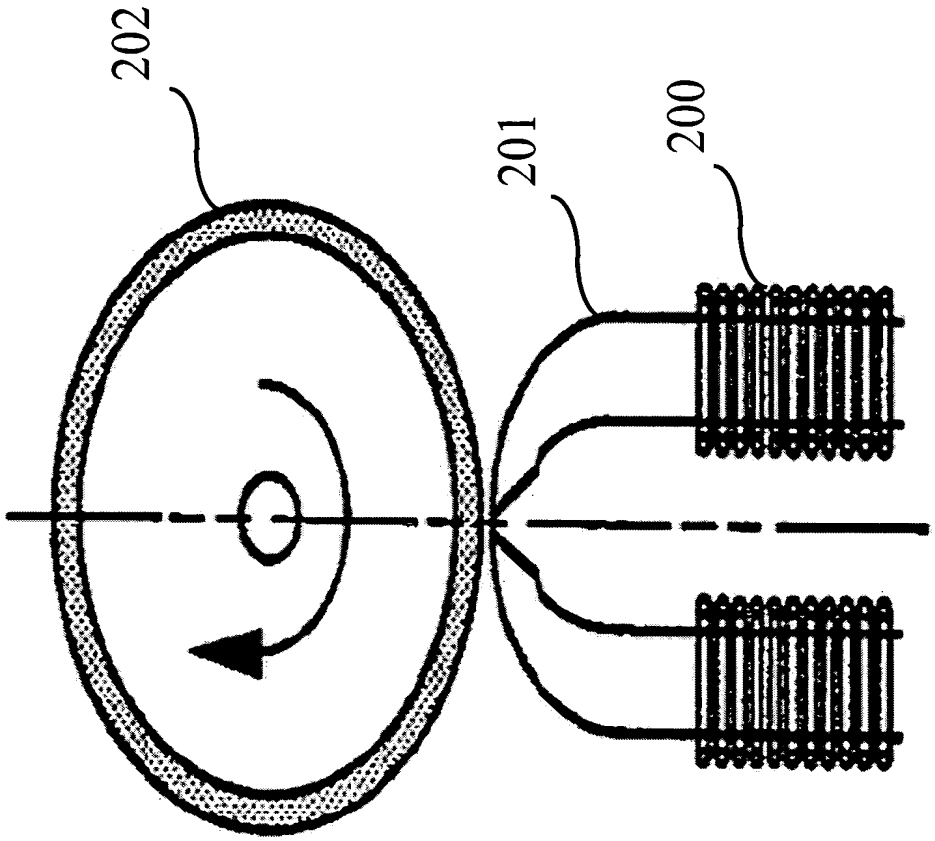


PRIOR ART

FIG. 1

BEST AVAILABLE COPY



PRIOR ART

FIG. 2

BEST AVAILABLE COPY

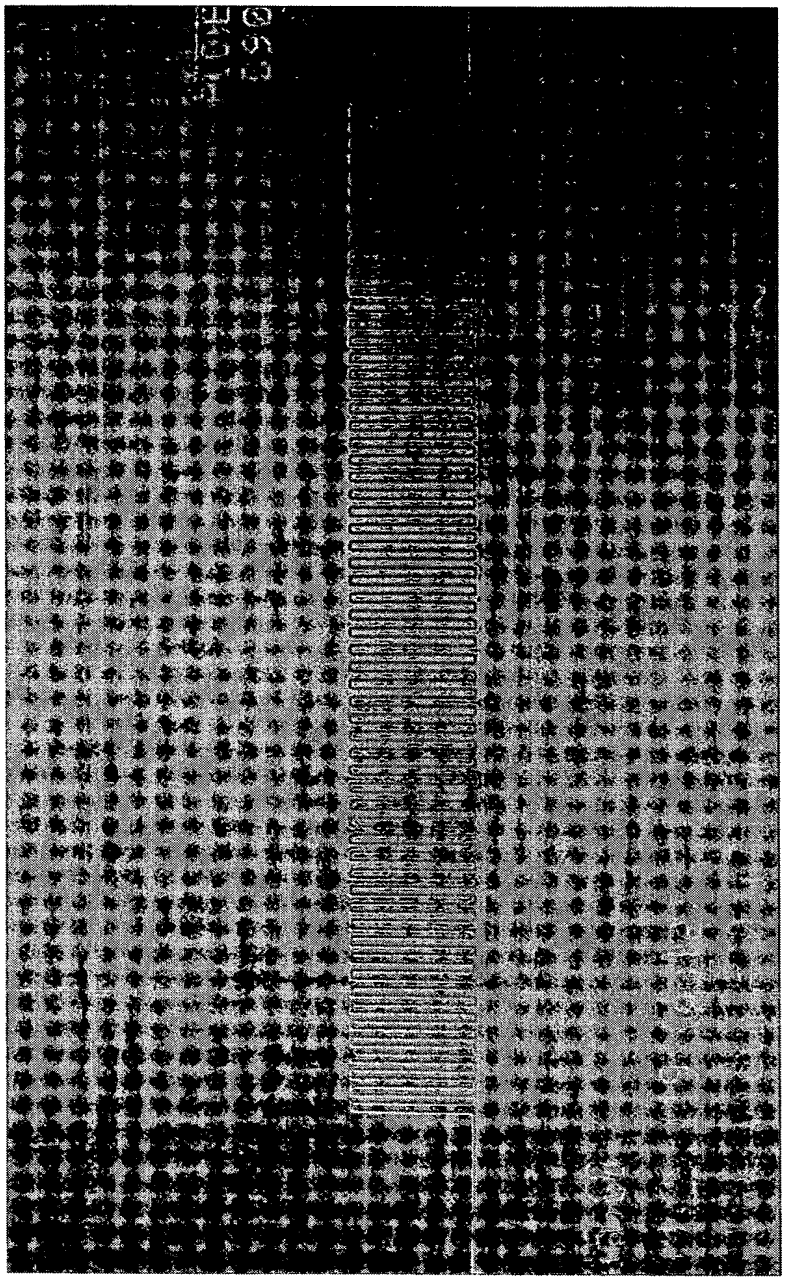


FIG. 3

BEST AVAILABLE COPY

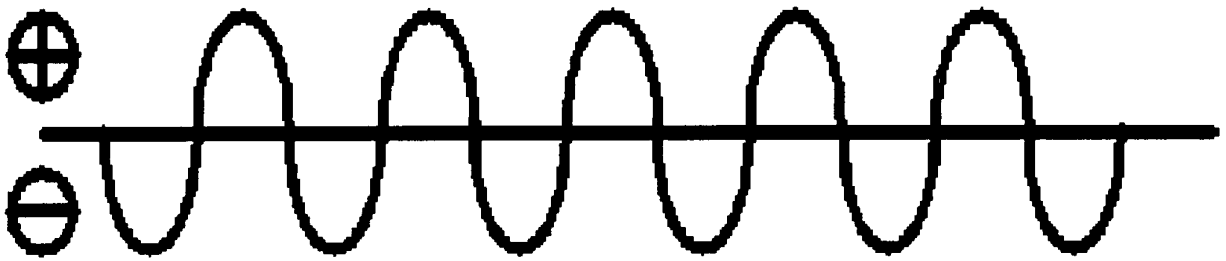


FIG. 4

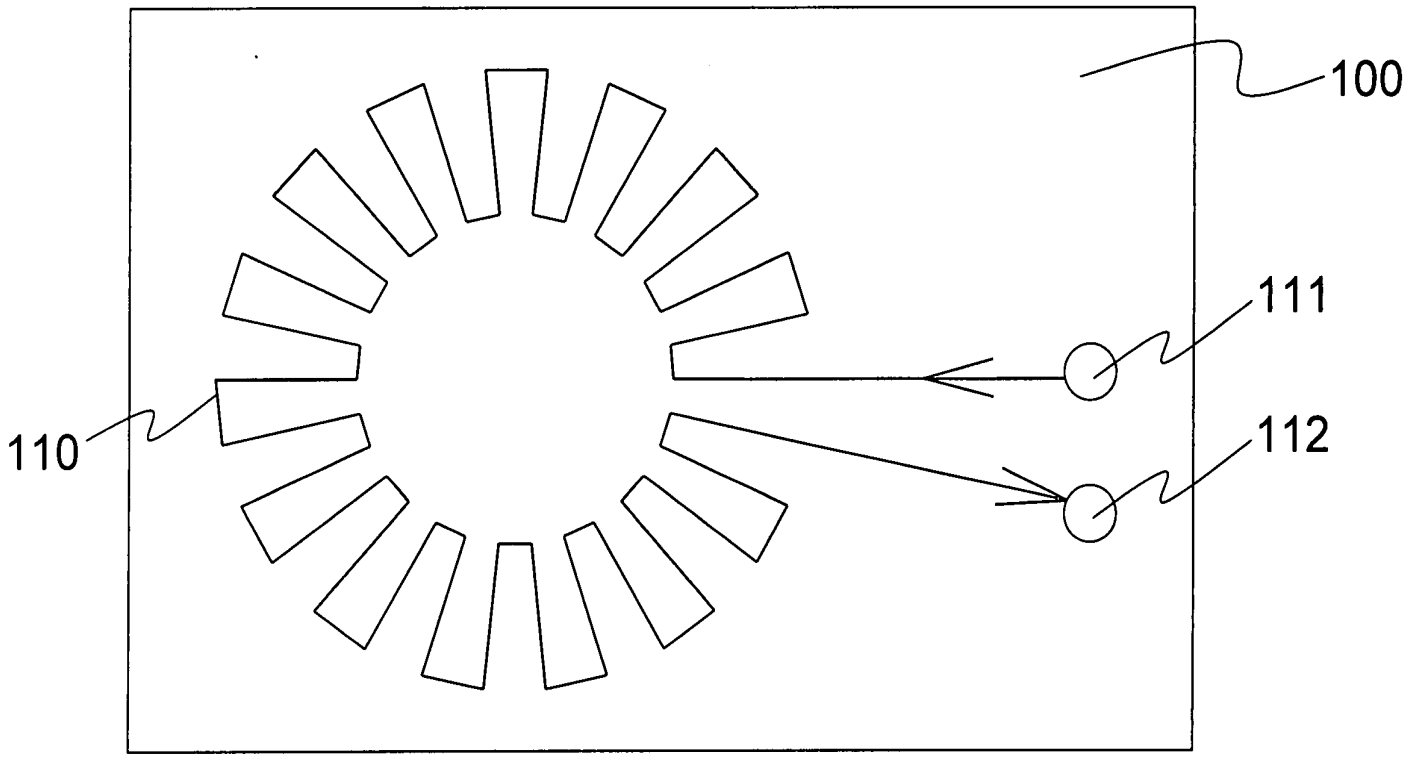


FIG. 5

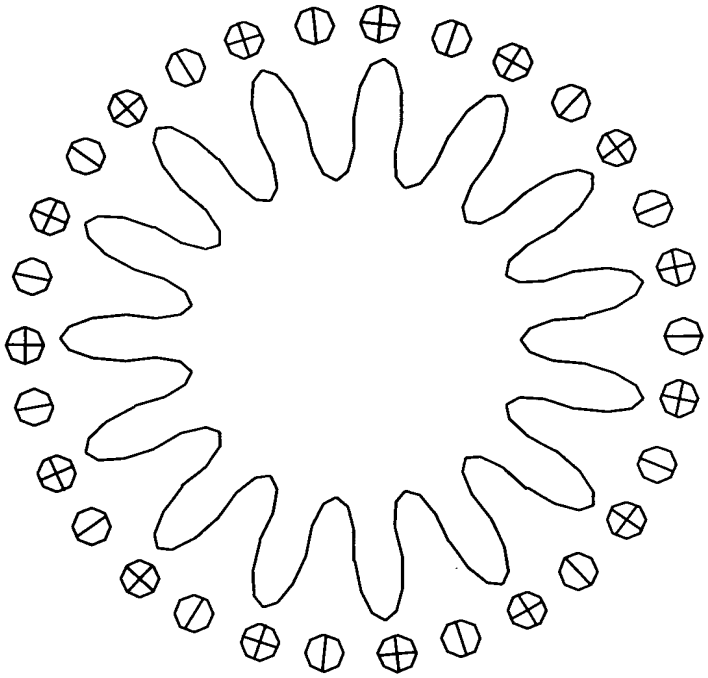


FIG. 6

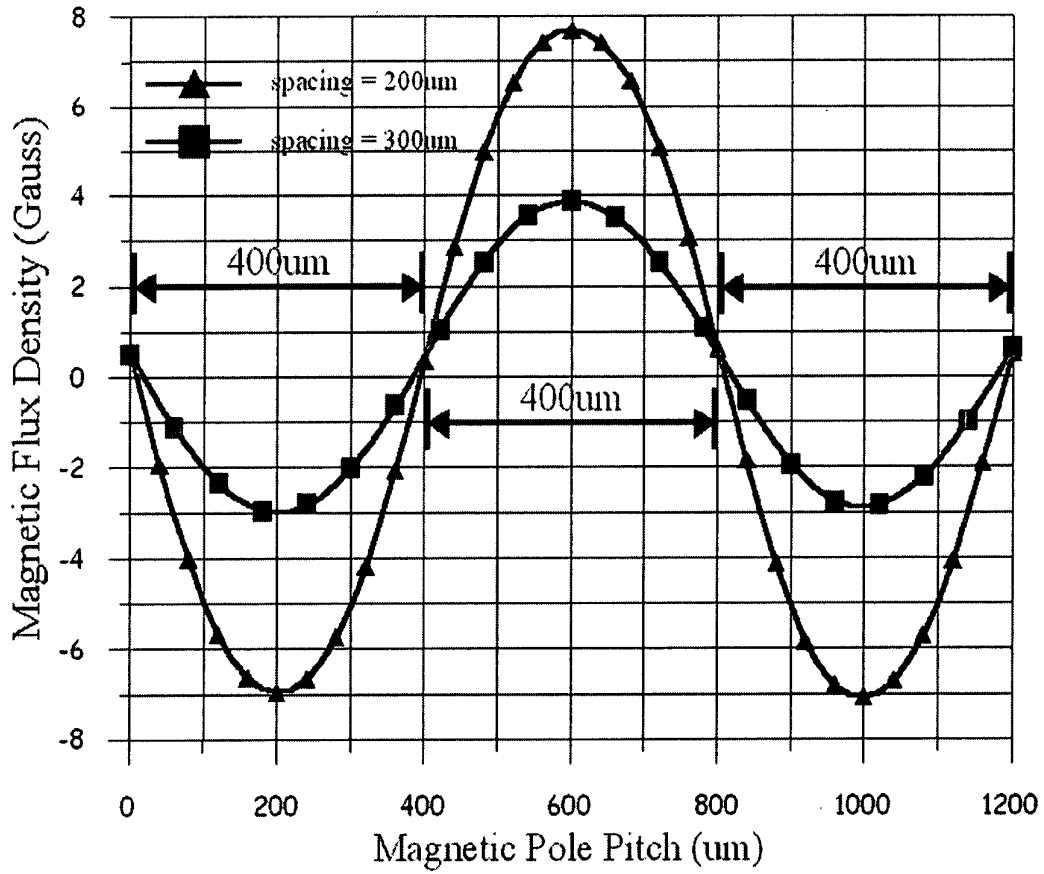

spacing = 200um
spacing = 300um
400um
400um
400um
Magnetic Flux Density (Gauss)
Magnetic Pole Pitch (um)
8
6
4
2
0
-2
-4
-6
-8
0
200
400
600
800
1000
1200

FIG. 7

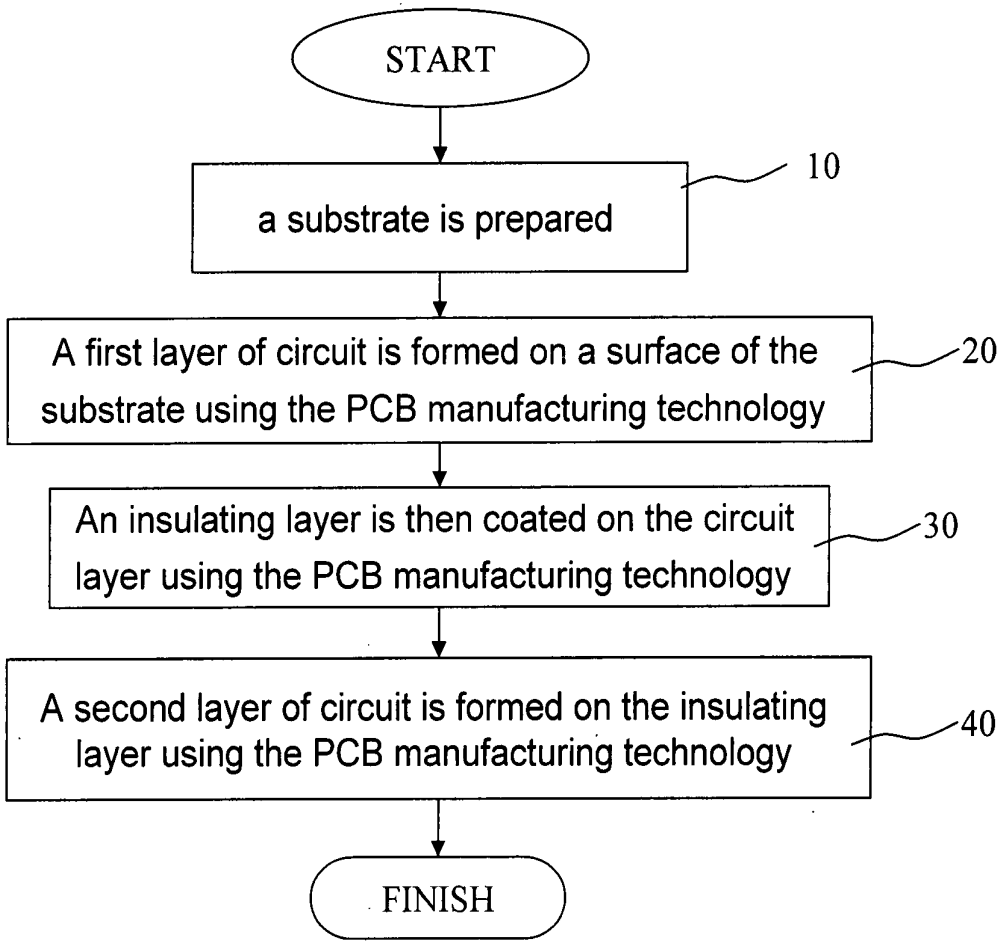

START
a substrate is prepared
10
A first layer of circuit is formed on a surface of the substrate using the PCB manufacturing technology
20
An insulating layer is then coated on the circuit layer using the PCB manufacturing technology
30
A second layer of circuit is formed on the insulating layer using the PCB manufacturing technology
40
FINISH

FIG. 8